

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Kie Y. Ahn et al.

Title:

SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

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We are transmitting herewith the following attached items (as indicated with an "X"):

A return postcard.

 $\frac{\mathbf{X}}{\mathbf{X}}$ A Response Under 1.116 (6 Pages).

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Box AF, Commissioner for Patents, Washington, D.C. 20231, on this 27 day of January, 2003.

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